

PACKAGE RELIABILITY REPORT
FOR

DS9098P, Chi Cheng, Pb-Free

Dallas Semiconductor

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Prepared by:

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Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor packages:

DS9098P, Chi Cheng, Pb-Free

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.

Package Description:

A description of this assembly can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.

Note: Due to the nature of the construction on this assembly, there is no operating life data collected

The reliability data follows. Some of the data in this report may be generic. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. If there are additional assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that assembly. Where appropriate, preconditioning is performed before all stresses and the bond crater test unless otherwise noted. The reliability data section includes the latest data available.

Assembly Information:

Assembly Site: Chi Cheng Enterprises (Taiwan)
 Pin Count: 2
 Package Type: BRICK (Pb-Free)
 Body Size: 0
 Mold Compound: Metal
 Lead Frame: Stainless Steel 302
 Lead Finish: Sn Plate/Ni/Stainless Steel
 Die Attach: ?
 Bond Wire / Size: /
 Flammability: UL 94-V0
 Theta JA:
 Theta JC:
 Moisture Sensitivity (JEDEC J-STD20A) Level 1
 Date Code Range: 0542 to 0542

PACKAGE TESTS

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QTY	FAILS	FA#
SOLDERABILITY (Sn/Pb)	0542	JESD22-B102, COND C		15	0	
SOLDERABILITY (Pb-Free)	0542	JESD22-B102, COND C		15	0	
Total:					0	

Assembly Information:

Assembly Site: Chi Cheng Enterprises (Taiwan)
Pin Count: 2
Package Type: BRICK (Pb-Free)
Body Size: 0
Mold Compound: Vectra S135 LCP
Lead Frame: Stainless Steel 302
Lead Finsh: Sn Plate/Ni/Stainless Steel
Die Attach: ?
Bond Wire / Size: /
Flammability: UL 94-V0
Theta JA:
Theta JC:
Moisture Sensitivity (JEDEC J-STD20A) Level 1
Date Code Range: 0509 to 0509

MOISTURE SENSITIVITY LEVEL 1

DESCRIPTION	DATE	CODE	CONDITION	READPOINT	QTY	FAILS	FA#
STORAGE LIFE	0509		125C	24 HRS	14		
MOISTURE SOAK			85 C/85% R.H.	168 HRS	14		
CONVECTION REFLOW			260C +/-5C	3 PASS	14		
EXTERNAL VISUAL			J-STD-020, 6.1a		14	0	
Total:						0	

MOISTURE SENSITIVITY LEVEL 3

DESCRIPTION	DATE	CODE	CONDITION	READPOINT	QTY	FAILS	FA#
STORAGE LIFE	0509		125C	24 HRS	15		
MOISTURE SOAK			30C/60% R.H.	192 HRS	15		
CONVECTION REFLOW			260C +/-5C	3 PASS	15		
EXTERNAL VISUAL			J-STD-020, 6.1a		15	0	
Total:						0	

PACKAGE TESTS

DESCRIPTION	DATE	CODE	CONDITION	READPOINT	QTY	FAILS	FA#
SOLDERABILITY (Sn/Pb)	0509		JESD22-B102, COND C		8	0	
SOLDERABILITY (Pb-Free)	0509		JESD22-B102, COND C		8	0	
Total:						0	